

Customized to Your Needs

To make sure your implants benefit from the innovation of our components we are building on industry standards of connectivity options. Through a large network of partners we cover the full range of connectivity solutions according to your requirements.

High Integration Density

Varying interconnection technologies together with highly skilled manual cable manufacturing enable high channel counts per cable compared to other manufacturers.

High Variability

Versatile electrode and substrate materials connect almost any electrode material — from a variety of flexible wires to rigid FR4 substrates for PCBs or even ceramics.

Reliable Process Portfolio

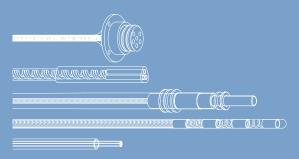
A wide range of processes are validated for the most common material combinations. Equally high standards for customer individual solutions are guaranteed.

Functionality Enhancement of Commercially Available Solutions

Commercially available connectors can be customized with custom interconnections to create new solutions for previously unsolved implant wiring challenges.

Cable Manufacturing

- Bundled straight wires
- · Coil winding cables
- · Ribbon cables



Interconnection Technologies

- · Ball-stud bonding
- · Laser welding
- Spot welding
- Parallel gap welding
- Micro soldering

Research Standard Connectivity

- ZIF connectors
- Omnetics connectors
- Harwin connectors
- Molex connectors
- Other connector types can be attached upon request

Medical Standard Connectivity

- IS-1
- DF-
- Bal Seal
 Medtronic
 Extension

To guarantee highest reliability our interconnections are tested to fulfill different standards in the medical device industry (e.g. EN 45502-1 or ISO 14708-1).

For particularly challenging mechanical requirements we are happy to engineer strain relieving concepts for your individual interconnection solution.

WIRES

ES INSULATION

- Platinum-Iridium (90/10)
- MP35N
- MP-DFT Ag (silver core)
- Gold

INSULATION

- Polyesterimide
- Fluoropolymer

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Silicone

SUBSTRATES

- Printed Circuit Board, e.g. FR4
- Screen printed ceramics
- Other materials upon request





